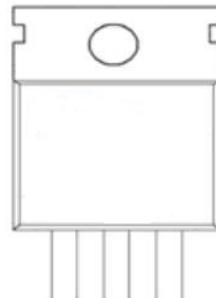
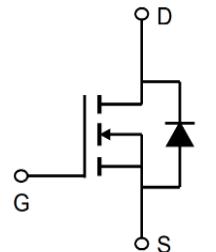


107V N-Channel Enhancement Mode MOSFET
Description

The 80N10 T uses advanced technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


General Features

$V_{DS} = 107V$ $I_D = 80A$

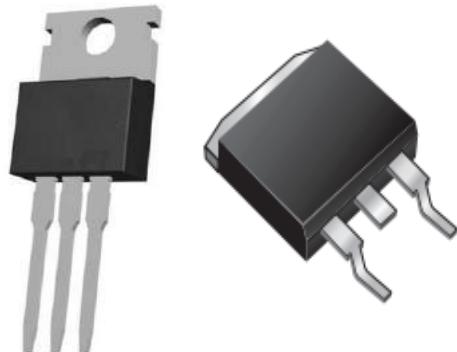
$R_{DS(ON)} < 9.0m\Omega$ @ $V_{GS}=10V$ (Type: 7.2m Ω)

Application

Isolated DC

Motor control

Synchronous-rectification


Absolute Maximum Ratings ($T_c=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	107	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^{\circ}C$	Continuous Drain Current ¹	80	A
$I_D@T_A=70^{\circ}C$	Continuous Drain Current ¹	62	A
IDM	Pulsed Drain Current ²	210	A
EAS	Single Pulse Avalanche Energy ³	100	mJ
IAS	Avalanche Current	15	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	100	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	1.25	$^{\circ}C/W$

107V N-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	107	111	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	---	7.2	9.0	$\text{m}\Omega$
	Static Drain-Source On-Resistance ²	$V_{GS}=4.5\text{V}$, $I_D=12\text{A}$	---	9.0	11	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
IDSS	Drain-Source Leakage Current	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
Qg	Total Gate Charge (10V)	$V_{DS}=50\text{V}$, $V_{GS}=10\text{V}$, $I_D=25\text{A}$	---	49.9	---	nC
Qg	Total Gate Charge (4.5V)		---	6.5	---	
Qgs	Gate-Source Charge		---	12.4	---	
Qgd	Gate-Drain Charge		---	3.4	---	
Td(on)	Turn-On Delay Time	$V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $R_G=2.2\Omega$, $I_D=25\text{A}$	---	20.6	---	ns
Tr	Rise Time		---	5	---	
Td(off)	Turn-Off Delay Time		---	51.8	---	
Tf	Fall Time		---	9	---	
Ciss	Input Capacitance	$V_{DS}=50\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	2640	---	pF
Coss	Output Capacitance		---	361	---	
Crss	Reverse Transfer Capacitance		---	6.5	---	
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	5	A
VSD	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=30\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.3	V
trr	Reverse Recovery Time	$V_r=50\text{V}$ $I_S=12\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	60.4	---	nS
Qrr	Reverse Recovery Charge		---	106	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{DD}=30\text{V}$, $V_{GS}=10\text{V}$, $L=0.3\text{ mH}$, starting $T_J=25^\circ\text{C}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Characteristics

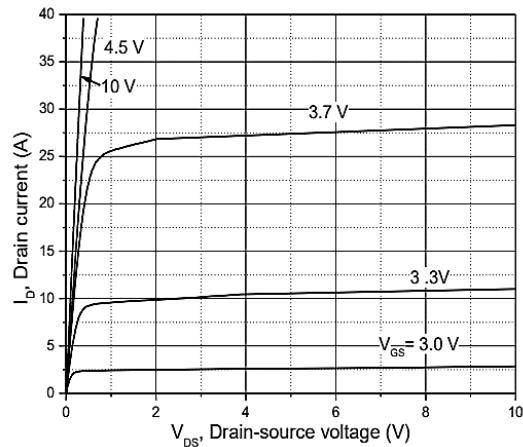


Figure 1. Typ. output characteristics

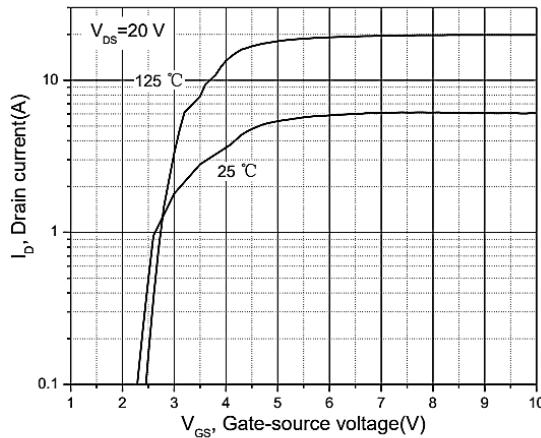


Figure 2. Typ. transfer characteristics

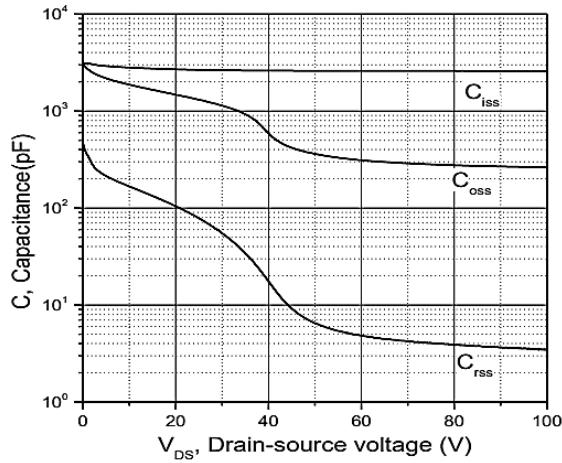


Figure 3. Typ. capacitances

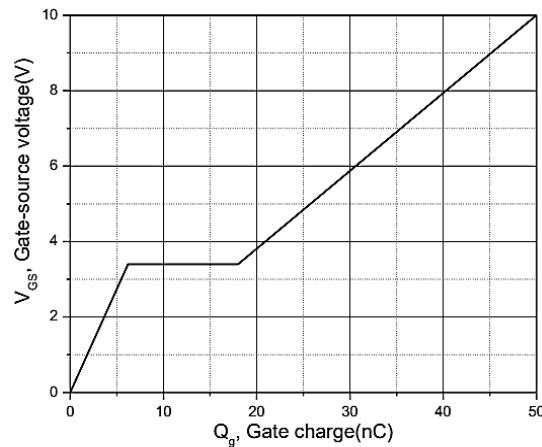


Figure 4. Typ. gate charge

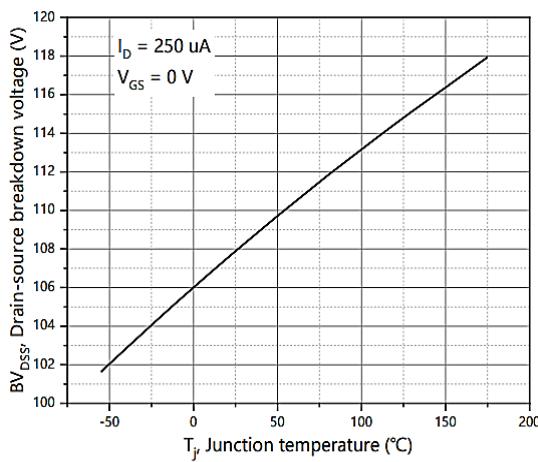


Figure 5. Drain-source breakdown voltage

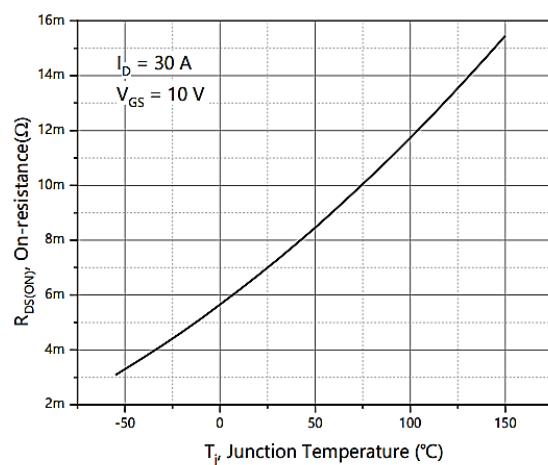


Figure 6. Drain-source on-state resistance



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107V N-Channel Enhancement Mode MOSFET

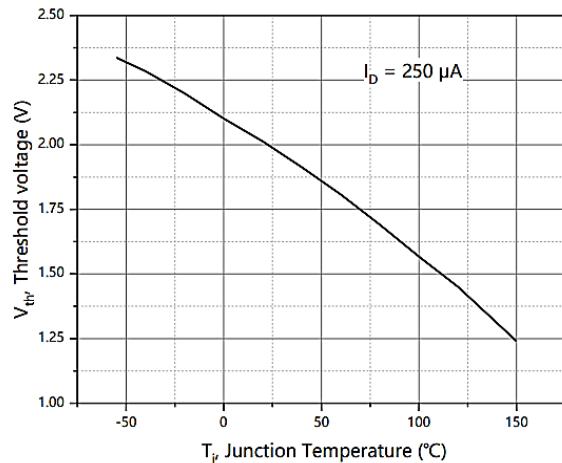


Figure 7. Threshold voltage

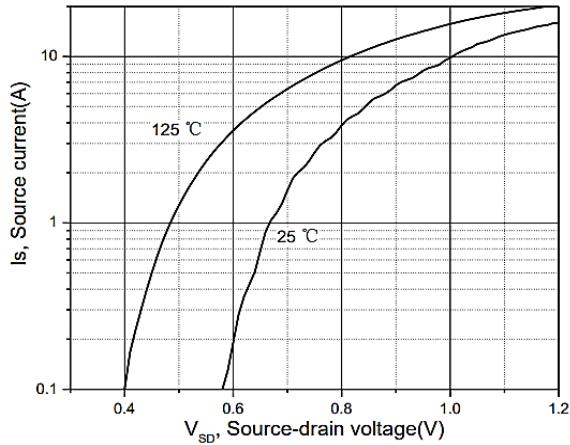


Figure 8. Forward characteristic of body diode

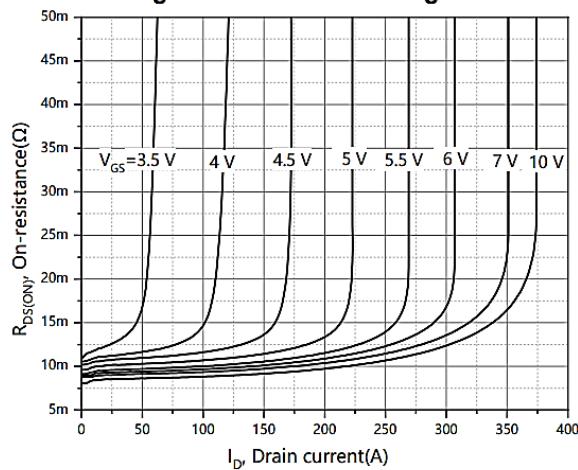


Figure 9. Drain-source on-state resistance

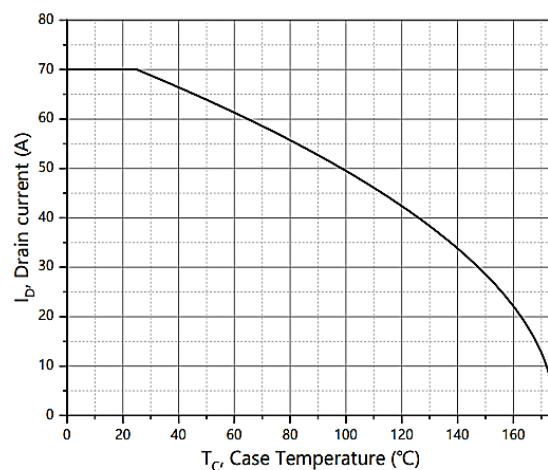


Figure 10. Drain current

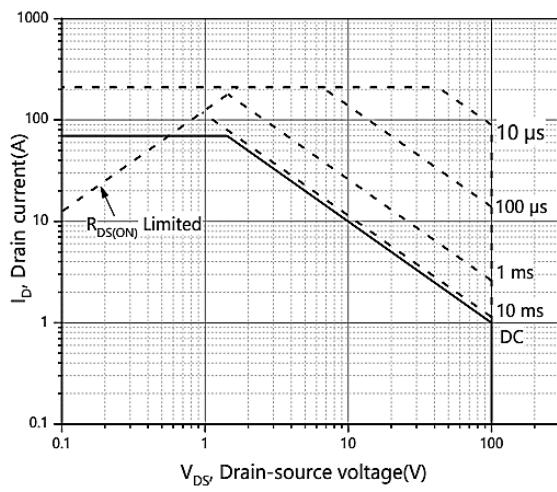


Figure 11. Safe operation area $T_c=25\text{ }^{\circ}\text{C}$

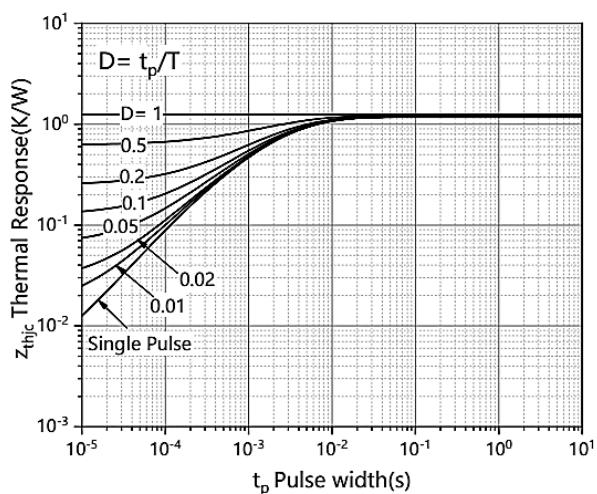
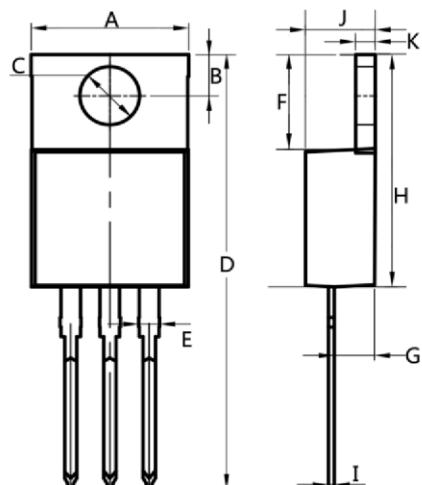
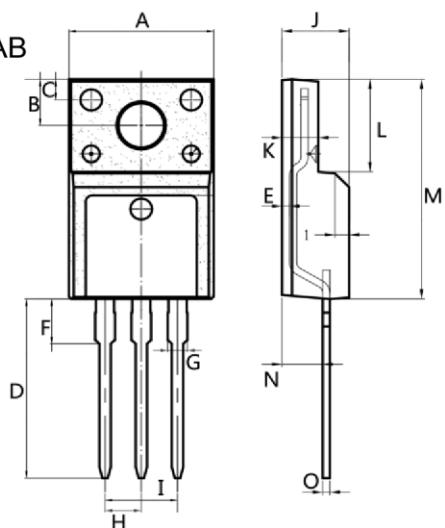


Figure 12. Max. transient thermal impedance

TO-220AB


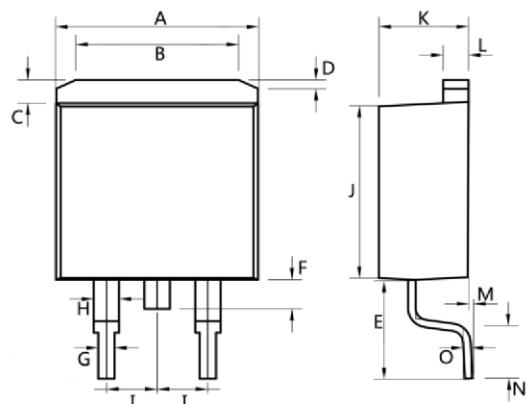
Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

ITO-220AB


Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter

TO-263


Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter